

# HIGH-SPEED/HIGH-DENSITY OPEN-PIN-FIELD

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?SEAF](http://www.samtec.com?SEAF)

**Insulator Material:**

Black LCP

**Contact Material:**

Copper Alloy

**Operating Temp Range:**

-55 °C to +125 °C

**Current Rating**

(7 mm stack height):

2.7 A per pin

(10 adjacent pins powered)

**Plating:**

Au or Sn over

50 μ" (1.27 μm) Ni

**Working Voltage:**

240 VAC

**RoHS Compliant:**

Yes

**Lead-Free Solderable:**

Yes

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



## STANDARDS

- VITA 47
- VITA 57.1 FMC
- VITA 57.4 FMC+
- VITA 74 VNX

## PROTOCOLS

- 100 GbE
- Fibre Channel
- Rapid I/O
- PCI Express®
- SATA
- InfiniBand™

**Notes:**  
Patented

IPC-A-610F and IPC J-STD-001F Class 3 solder joint.

Some sizes, styles and options are non-standard, non-returnable.

**Board Mates:**  
SEAM, SEAMP,  
SEAR, SEAMI

**Cable Mates:**  
SEAC\*

**Standoffs:**  
JSO

## IN DEVELOPMENT\*

- Connector (SE AFC) optimized for cable application. Contact Samtec.

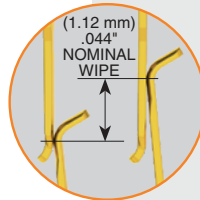
## HIGH-SPEED CHANNEL PERFORMANCE

SEAF/SEAM @ 10 mm Mated Stack Height

Rating based on Samtec reference channel. For full SI performance data visit [Samtec.com](http://Samtec.com) or contact [SIG@samtec.com](mailto:SIG@samtec.com)

PAM 4

56  
Gbps



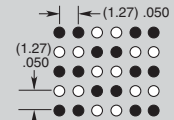
Up to 500 pins

Low insertion/extraction forces

Solder charges

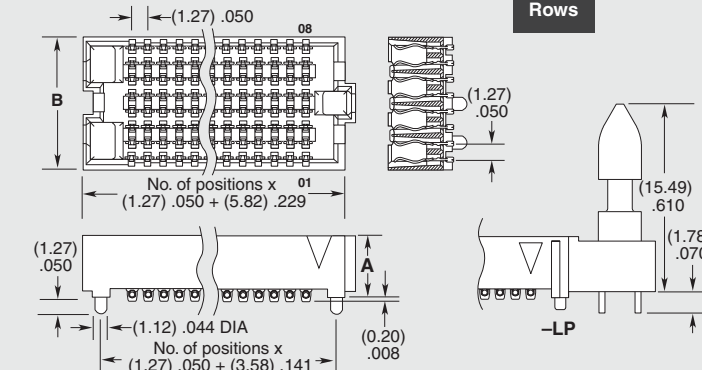


## DIFFERENTIAL SIGNAL ROUTING

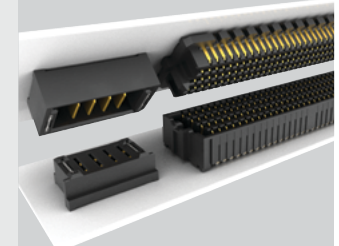


The above signal routing configuration allows for the use of 25 to 125 differential pair counts. Contact [sig@samtec.com](mailto:sig@samtec.com) for specific details.

SEAF	NO. PINS PER ROW	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	A	OPTION	K	TR										
		Specify LEAD STYLE from chart																	
	-10, -15, -20, -30, -40, -50 (-10 only available in 04 row) (-15 only available in 04 or 10 row with -05.0 lead style)	<table border="1"> <thead> <tr> <th>LEAD STYLE</th> <th>A</th> </tr> </thead> <tbody> <tr> <td>-05.0</td> <td>(5.05) .199</td> </tr> <tr> <td>-06.0</td> <td>(6.05) .238</td> </tr> <tr> <td>-06.5</td> <td>(6.55) .258</td> </tr> <tr> <td>-07.5</td> <td>(7.54) .297</td> </tr> </tbody> </table>	LEAD STYLE	A	-05.0	(5.05) .199	-06.0	(6.05) .238	-06.5	(6.55) .258	-07.5	(7.54) .297	-L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on solder tail  -S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on solder tail	-04 = Four Rows -05 = Five Rows -06 = Six Rows -08 = Eight Rows -10 = Ten Rows	-1 = Tin/Lead Alloy Solder Charge -2 = Lead-Free Solder Charge		-LP = Latch Post (-LP required for SEAC mate only) (Available with -05.0 lead style and -04, -06, -08 & -10 rows only)	-K = Polyimide film Pick & Place Pad (Not available with -10 and -15 pins with -LP Latch post)	
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## POWER/SIGNAL APPLICATION



Compatible with UMPT/UMPS for flexible two-piece power/signal solutions

Due to technical progress, all designs, specifications and components are subject to change without notice.